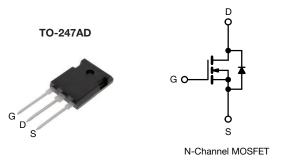
SiHW80N60E

Vishay Siliconix



E Series Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.026		
Q _g max. (nC)	443			
Q _{gs} (nC)	85			
Q _{gd} (nC)	139			
Configuration	Single			

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-247AD
Lead (Pb)-free and halogen-free	SiHW80N60E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \text{ °C}$, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-source voltage			V _{DS}	600	V		
Gate-source voltage			V _{GS}	± 30			
Continuous drain current (T _J = 150 °C)	V at 10 V	$T_{C} = 25 \text{ °C}$ $T_{C} = 100 \text{ °C}$	- I _D	80			
	V _{GS} at 10 V	T _C = 100 °C		51	А		
Pulsed drain current ^a			I _{DM}	268			
Linear derating factor				4.2	W/°C		
Single pulse avalanche energy ^b			E _{AS}	1142	mJ		
Maximum power dissipation			PD	520	W		
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope	T _J = 125 °C		als s / alt	70	V/ns		
Reverse diode dv/dt ^d		dv/dt	8.8	v/ns			
Soldering recommendations (peak temperature) ^c	For 10 s			300	°C		

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. $V_{DD} = 140$ V, starting $T_J = 25$ °C, L = 28.2 mH, $R_q = 25 \Omega$, $I_{AS} = 9$ A

c. 1.6 mm from case

d. $I_{SD} \leq I_D$, di/dt = 100 A/µs, starting T_J = 25 °C

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COMPLIANT HALOGEN

FREE



Vishay Siliconix

THERMAL RESISTANCE RATI	1							
PARAMETER	SYMBOL	TYP.	MA			UNIT		
Maximum junction-to-ambient	R _{thJA}	-	40			°C/W		
Maximum junction-to-case (drain)	R _{thJC}	- 0.24						
SPECIFICATIONS (T _J = 25 °C, u	Inless otherw	ise noted)						
PARAMETER	SYMBOL		T CONDITIONS	MIN.	TYP.	MAX.	UNI	
Static				1	1	1		
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	600	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_J$		e to 25 °C, I _D = 1 mA	-	0.68	-	V/°C	
Gate-source threshold voltage (N)	V _{GS(th)}		· V _{GS} , I _D = 250 μA	2	-	4	V	
			$V_{GS} = \pm 20 V$		-	± 100	nA	
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 V$		-	± 1	μA	
		V _{DS} =	600 V, V _{GS} = 0 V	-	-	1	· .	
Zero gate voltage drain current	I _{DSS}	-	, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 40 A	-	0.026	0.030	Ω	
Forward transconductance	g _{fs}	V _{DS}	= 30 V, I _D = 40 A	-	20	-	S	
Dynamic		1 -				1		
Input capacitance	C _{iss}		V _{GS} = 0 V,		6900	-	pF	
Output capacitance	C _{oss}	$V_{\rm DS} = 100 V,$ $f = 1 \rm MHz$		-	327	-		
Reverse transfer capacitance	C _{rss}			-	6	-		
Effective output capacitance, energy related ^a	C _{o(er)}			-	224	-		
Effective output capacitance, time related ^b	C _{o(tr)}	$V_{\rm DS} = 0$	$V_{DS} = 0 V$ to 480 V, $V_{GS} = 0 V$		1092	-		
Total gate charge	Q _g			-	295	443		
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_{D} = 40 \text{ A}, V_{DS} = 480 \text{ V}$	-	85	-	nC	
Gate-drain charge	Q _{gd}			-	139	-		
Turn-on delay time	t _{d(on)}			-	63	95	- ns	
Rise time	t _r	V _{DD} =	V _{DD} = 480 V, I _D = 40 A,		153	230		
Turn-off delay time	t _{d(off)}	$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$		-	239	359		
Fall time	t _f			-	147	221		
Gate input resistance	R _g	f = 1 MHz, open drain		0.6	1.2	2.4	Ω	
Drain-Source Body Diode Characteristic	cs							
Continuous source-drain diode current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	80	A	
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	268		
Diode forward voltage	V _{SD}	$T_J = 25 \text{ °C}, I_S = 40 \text{ A}, V_{GS} = 0 \text{ V}$		-	-	1.2	V	
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_{S = 40 \text{ A}},$ dI/dt = 100 A/µs ^{, V} _R = 25 V		-	746	1492	ns	
Reverse recovery charge	Q _{rr}			-	16	32	μC	
Reverse recovery current	I _{RRM}			-	33	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

b. Coss(tr) is a fixed capacitance that gives the same charging time as Coss while VDS is rising from 0 % to 80 % VDSS

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

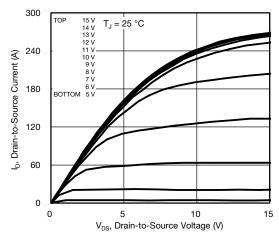
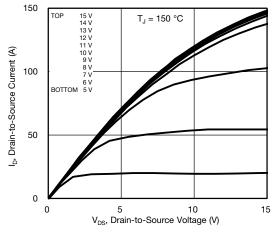


Fig. 1 - Typical Output Characteristics





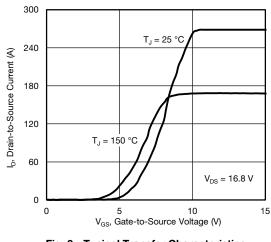
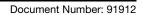


Fig. 3 - Typical Transfer Characteristics

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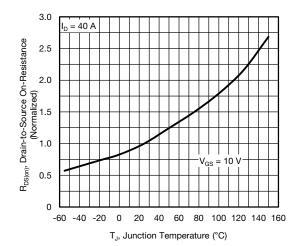


Fig. 4 - Normalized On-Resistance vs. Temperature

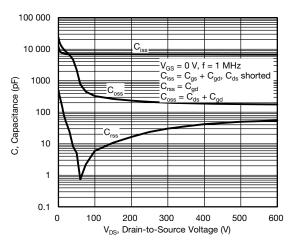
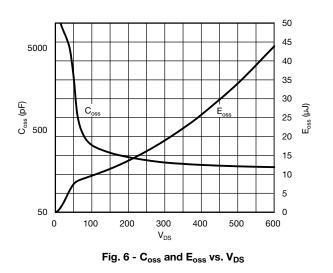


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



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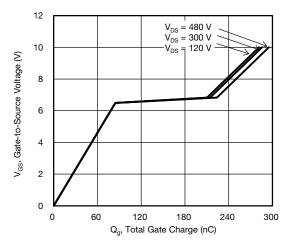


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

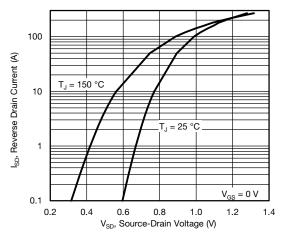
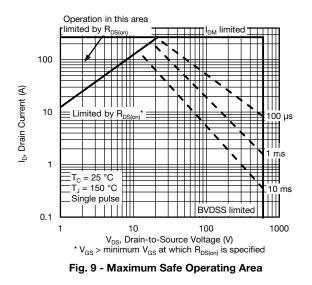


Fig. 8 - Typical Source-Drain Diode Forward Voltage



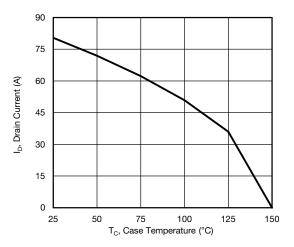


Fig. 10 - Maximum Drain Current vs. Case Temperature

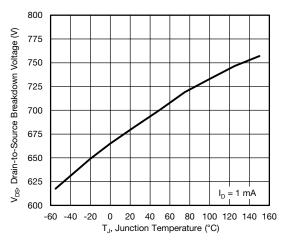
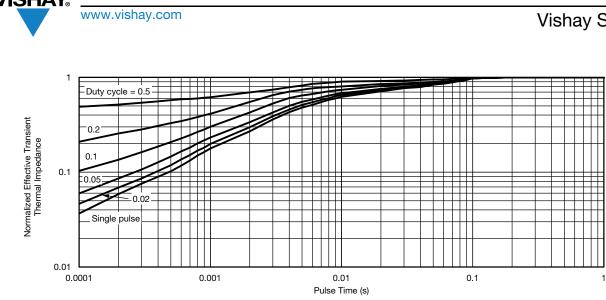


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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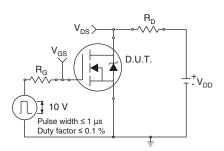


Fig. 13 - Switching Time Test Circuit

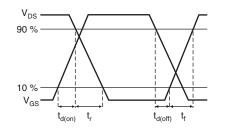


Fig. 14 - Switching Time Waveforms

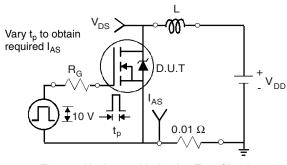


Fig. 15 - Unclamped Inductive Test Circuit

V_{DS} V_{DD} V_{DS} I_{AS}

Fig. 16 - Unclamped Inductive Waveforms

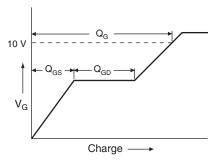
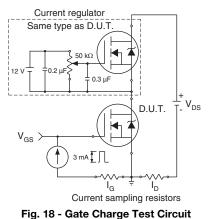


Fig. 17 - Basic Gate Charge Waveform



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Peak Diode Recovery dV/dt Test Circuit

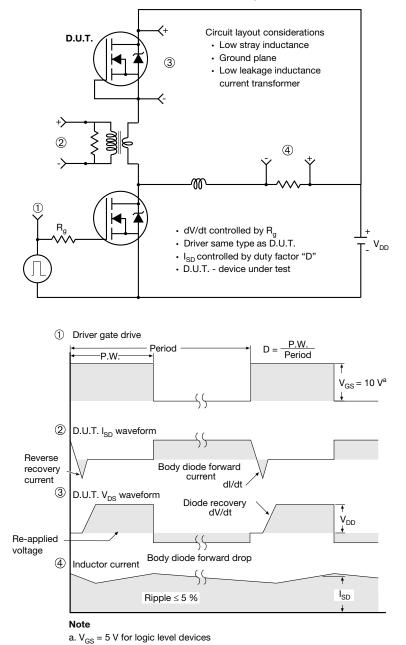


Fig. 19 - For N-Channel

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